

ABSTRACT

A laminate including: a semiconductor substrate; a support substrate; and an adhesive layer provided between the semiconductor substrate and the support substrate, wherein

the adhesive layer is formed from a cured product of an adhesive composition,

the adhesive composition contains a polyorganosiloxane that has an alkenyl group having 2 to 40 carbon atoms and bonded to a silicon atom, a polyorganosiloxane having a Si-H group, a platinum group metal-based catalyst, and a crosslinking inhibitor, and

the crosslinking inhibitor contains at least one of a pyridine ring-containing compound and a phosphorus-containing organic compound.

FIG. 1